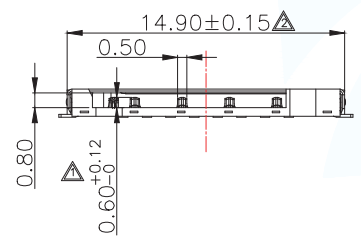
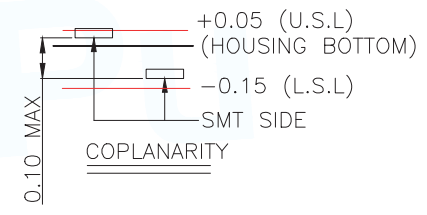


SECTION: A-A

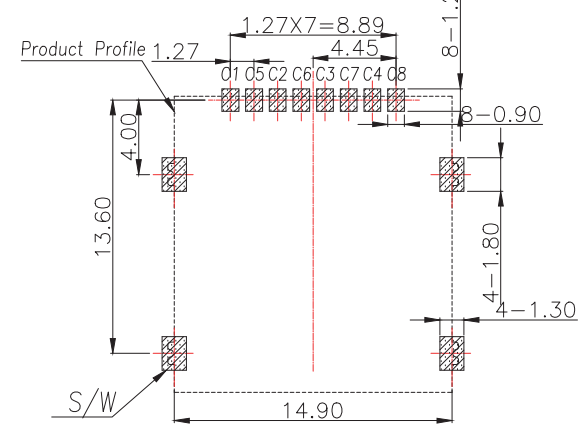
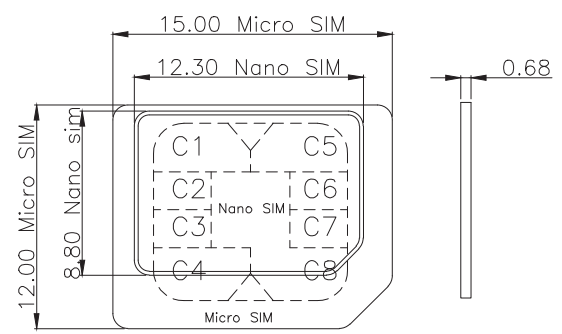
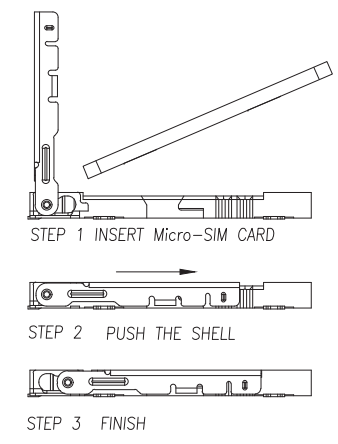
- NOTES:
- ELECTRICAL CHARACTERISTICS
 - 1-1. CONTACT RESISTANCE: 60 Milliohms Max
 - 1-2. INSULATION RESISTANCE: 1,000 Megohms Min.
 - 1-3. DIELECTRIC WITHSTANDING VOLTAGE: 500V AC FOR 1 MINUTE.
 - MECHANICAL CHARACTERISTICS
 - 2-1. OPERATION TEMPERATURE RANGE: -25°C~+70°C
 - 2-2. DURABILITY: 5000 CYCLES
 - MATERIAL:
 - 3-1. HOUSING: THERMOPLASTIC,UL 94-V0
 - 3-2. TERMINAL: PHOSPHOR BRONZE,T=0.15
 - 3-3. SHELL: STAINLESS STEEL,T=0.15
 - FINISHED:
 - 4-1. TERMINAL: Ni PLATED UNDER,Au PLATED ON CONTACT AREA,G/F PLATED ON SOLDER TAIL



WITHDRAWAL CARD		INSERT CARD	
GROUND PIN (C5)	Switch Pin (S/W)	GROUND PIN (C5)	Switch Pin (S/W)



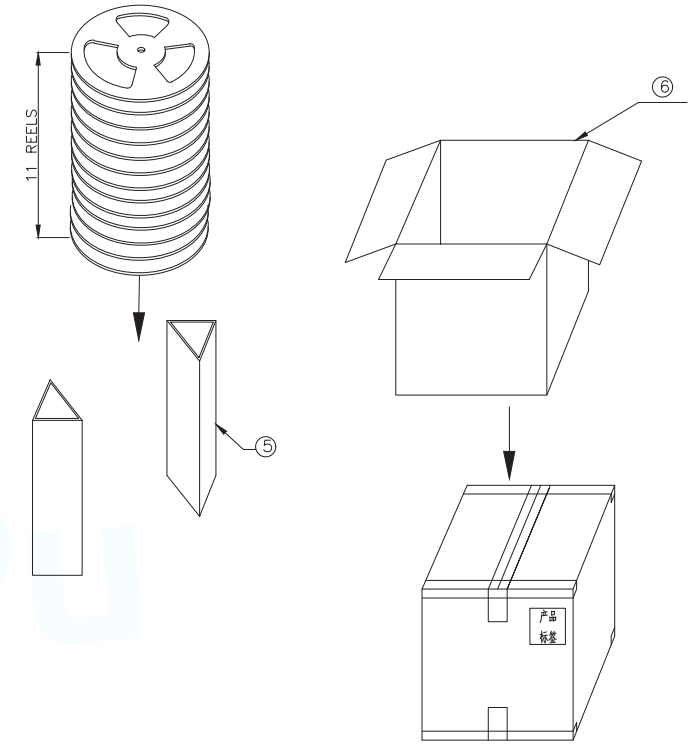
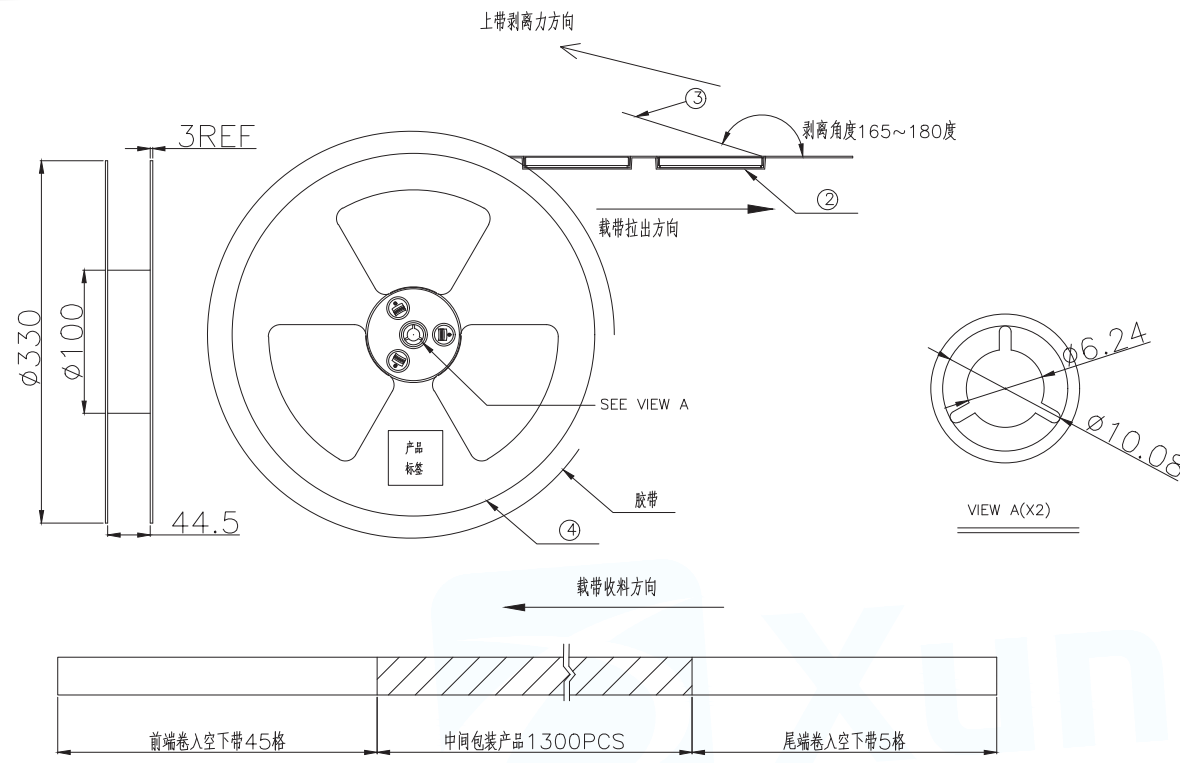
MICRO SIM CARD	
Pin No.	NAME
C1	VCC OF SIM
C2	RST OF SIM
C3	CLK OF SIM
C5	GND OF SIM
C6	VPP OF SIM
C7	I/O OF SIM
C4/C8	N/A
S/W	Switch Pin



PAD AREA
 KEEP OUT AREA

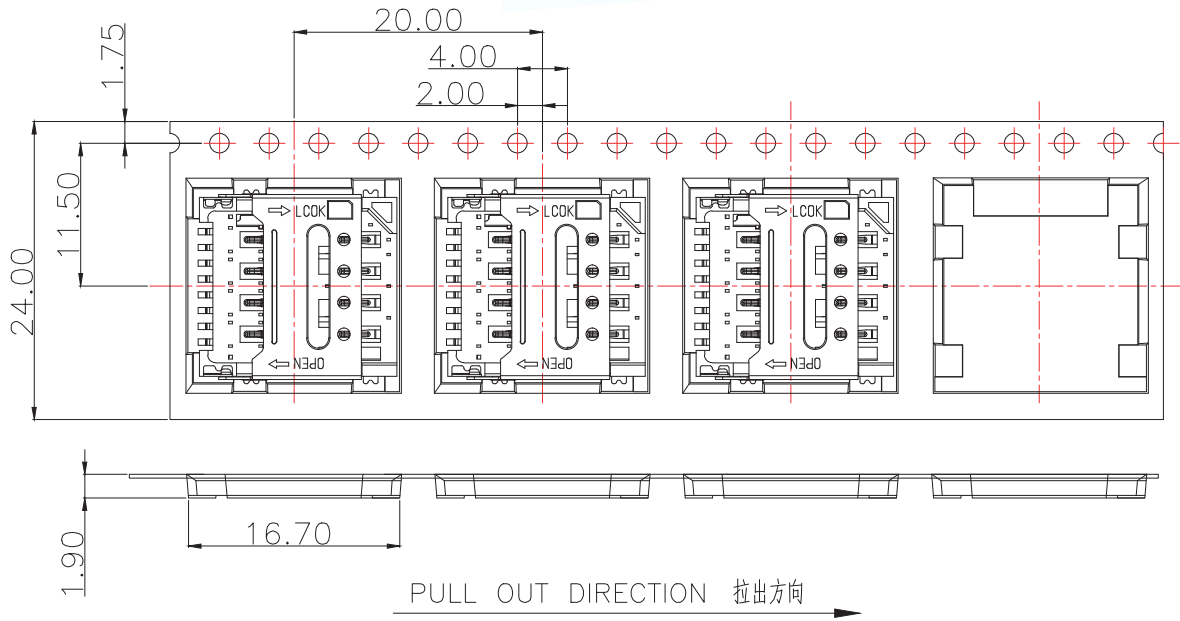
RECOMMENDED PCB LAYOUT
 GENERAL TOLERANCE ±0.05

MANUFACTURE DWG		东莞市讯普电子科技有限公司 DongGuan XunPu Electronics Co.,Ltd	
UNLESS OTHERWISE SPECIFIED TOLERANCES		TITLE: MICRO SIM CARD HINGED 8+1PIN H1.5 铰链式	
DECIMALS:	ANGLES:	PAR	SMC-220-ARP9
X.: ±0.5	X': ±5°	DWN	
X.X: ±0.25	X.X': ±3°	CHKD	
X.XX: ±0.12		APVD	
CUSTOMER COPY		SCALE: 1:1	UNIT: MM
		SIZE: A4	SHEET: 1F1
			REV: A



PACKING NOTES:

1. PRIMARY PACKING:1300PCS/REEL;
2. SECONDARY PACKING: 10 REELS/CARTON (13KPCS/CARTON)
3. PEELING RESISTANCE: 30gf~100gf
4. PEELING ANGLE:165°~180°
5. PEELING SPEED: 300mm/minutes.



MANUFACTURE DWG		 东莞市讯普电子科技有限公司 DongGuan XunPu Electronics Co.,Ltd		
UNLESS OTHERWISE SPECIFIED TOLERANCES			TITLE:MICRO SIM CARD HINGED 9PIN H1.5 掀盖式 包装图	
DECIMALS:	ANGLES:		PAR	SMC-220-ARP9
X.:±0.5	X'.:±5°		DWN	
X.X:±0.25	X.X':±3°		CHKD	
X.XX:±0.12		APVD		
CUSTOMER COPY		SCALE1:1	UNIT:MM	
		SIZE:A4	SHEET:1F1	REV:A